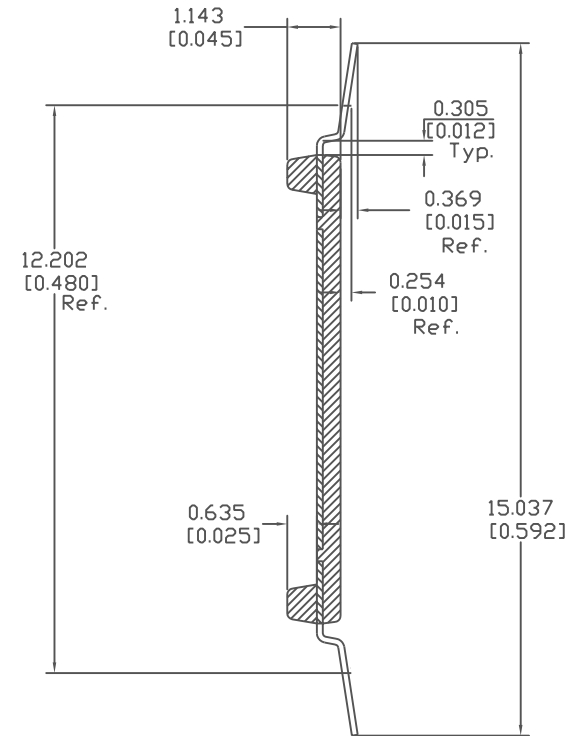
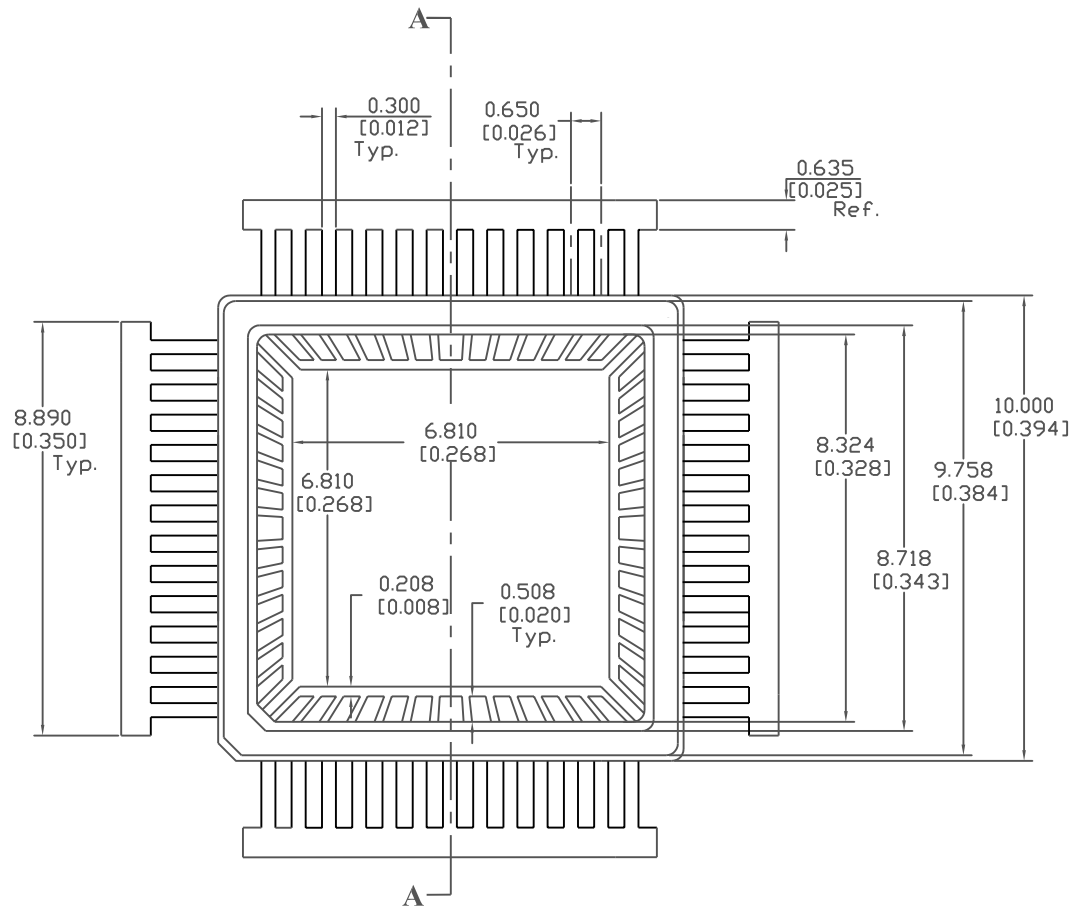


SSM P/N PLQ05201

ECN	REV.	DESCRIPTION	DATE:	APP'D:
10032	3	PRODUCTION-RELEASE	03/07/03	BF



Section A - A

NOTES:
 BODY : PLASTIC, SEMICONDUCTOR GRADE
 LEAD FRAME : COPPER, OLIN 194
 LEAD FINISH : 50uIN Au, OVER 30uIN NI
 FRAME THICKNESS : 0.127mm +/-0.0076mm [0.005*+/- 0.0003*]
 Die Pad : 6.810mm x 6.810mm [.268* x .268*]



TITLE: 52 Lead LQFP Open-Pak (10mm x 10mm)			
MATERIAL: SEE NOTES	SCALE: NONE	DRAWN BY: DBG	
GEN. TOL: ±.005	DATE: 01/29/03	APP'D: BF 03/07/03	
SSM P/N: PLQ05201	DWG. NO: LQFP52-OP-01	REV. 3	